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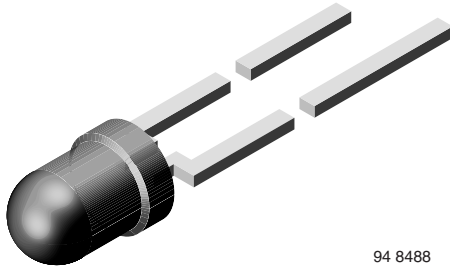
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High Speed Infrared Emitting Diode, 940 nm, GaAlAs, MQW



94 8488

DESCRIPTION

VSLB3948 is a high speed infrared emitting diode in GaAlAs, MQW technology, molded in a clear plastic package.

FEATURES

- Package type: leaded
- Package form: T-1, clear epoxy
- Dimensions: Ø 3 mm
- High speed
- High radiant power
- Low forward voltage
- Suitable for high pulse current operation
- Angle of half intensity: $\phi = \pm 22^\circ$
- Peak wavelength: $\lambda_p = 940$ nm
- Good spectral matching to Si photodetectors
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Infrared remote control units

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSLB3948	65	± 22	940	15

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSLB3948	Bulk	MOQ: 5000 pcs, 5000 pcs/bulk	T-1

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.1, t_p = 100 \mu\text{s}$	I_{FM}	500	mA
Surge forward current	$t_p = 100 \mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	160	mW
Junction temperature		T_j	100	$^\circ\text{C}$
Operating temperature range		T_{amb}	-25 to +85	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^\circ\text{C}$
Soldering temperature	$t \leq 5$ s, 2 mm from case	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R_{thJA}	300	K/W

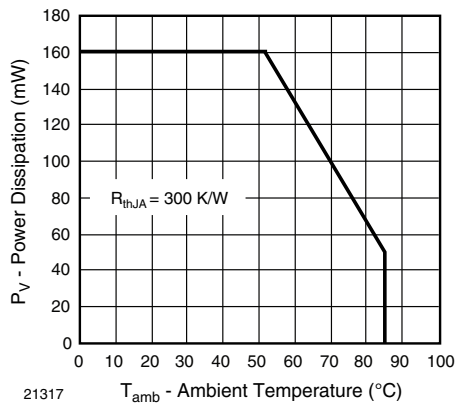


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

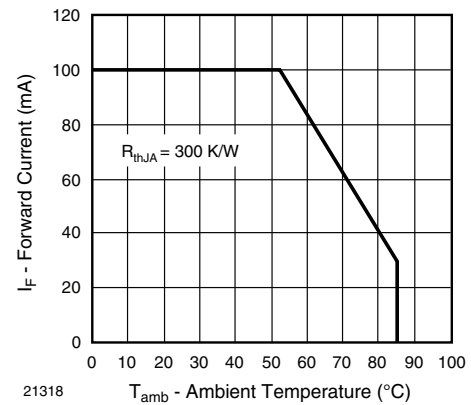
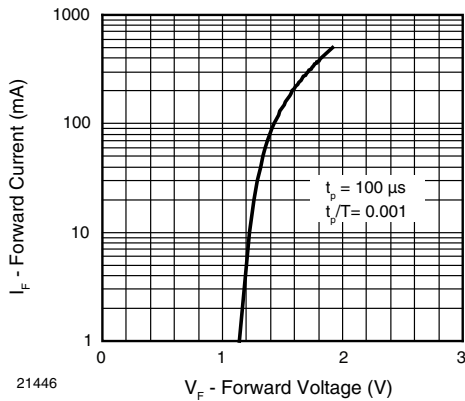


Fig. 2 - Forward Current Limit vs. Ambient Temperature

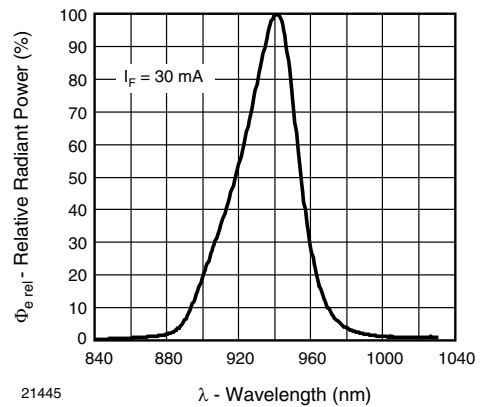
BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F	1.22	1.42	1.62	V
Temperature coefficient of V _F	I _F = 1 mA	TK _{V_F}		-1.5		mV/K
Reverse current	V _R = 5 V	I _R			10	μA
Junction capacitance	V _R = 0 V, f = 1 MHz, E = 0 mW/cm ²	C _J		21		pF
Radiant intensity	I _F = 100 mA, t _p = 20 ms	I _e	32	65	110	mW/sr
Radiant power	I _F = 100 mA, t _p = 20 ms	φ _e		40		mW
Temperature coefficient of radiant power	I _F = 1 mA	TK _{φ_e}		-1.1		%/K
	I _F = 100 mA	TK _{φ_e}		-0.51		%/K
Angle of half intensity		φ		± 22		deg
Peak wavelength	I _F = 30 mA	λ _p		940		nm
Spectral bandwidth	I _F = 30 mA	Δλ		30		nm
Temperature coefficient of λ _p	I _F = 30 mA	TK _{λ_p}		0.25		nm
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		15		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		15		ns
Virtual source diameter		d		2		mm

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)



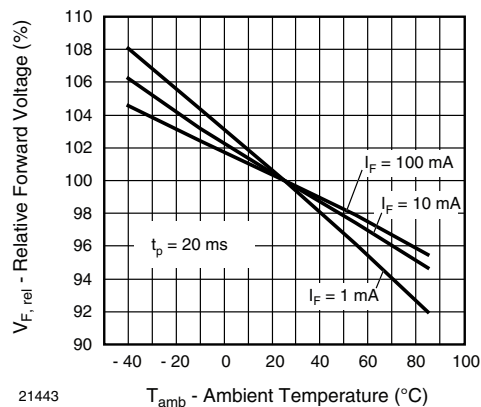
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Fig. 3 - Forward Current vs. Forward Voltage



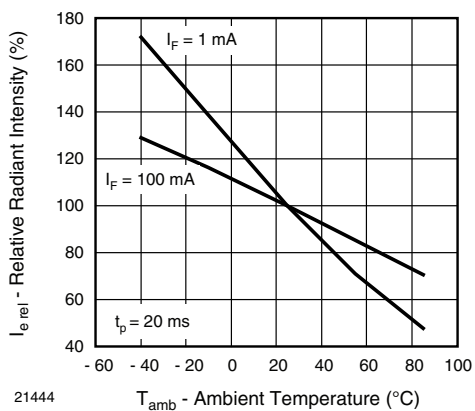
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Fig. 6 - Relative Radiant Power vs. Wavelength



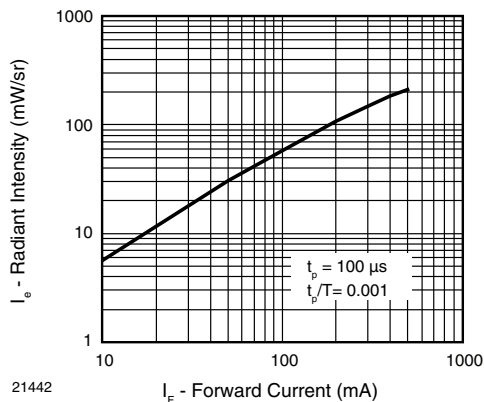
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Fig. 4 - Relative Forward Voltage vs. Ambient Temperature



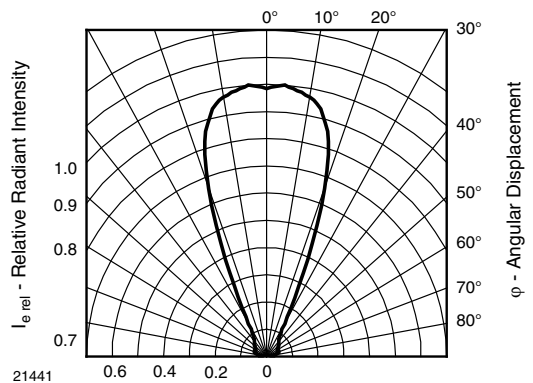
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Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature



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Fig. 5 - Radiant Intensity vs. Forward Current

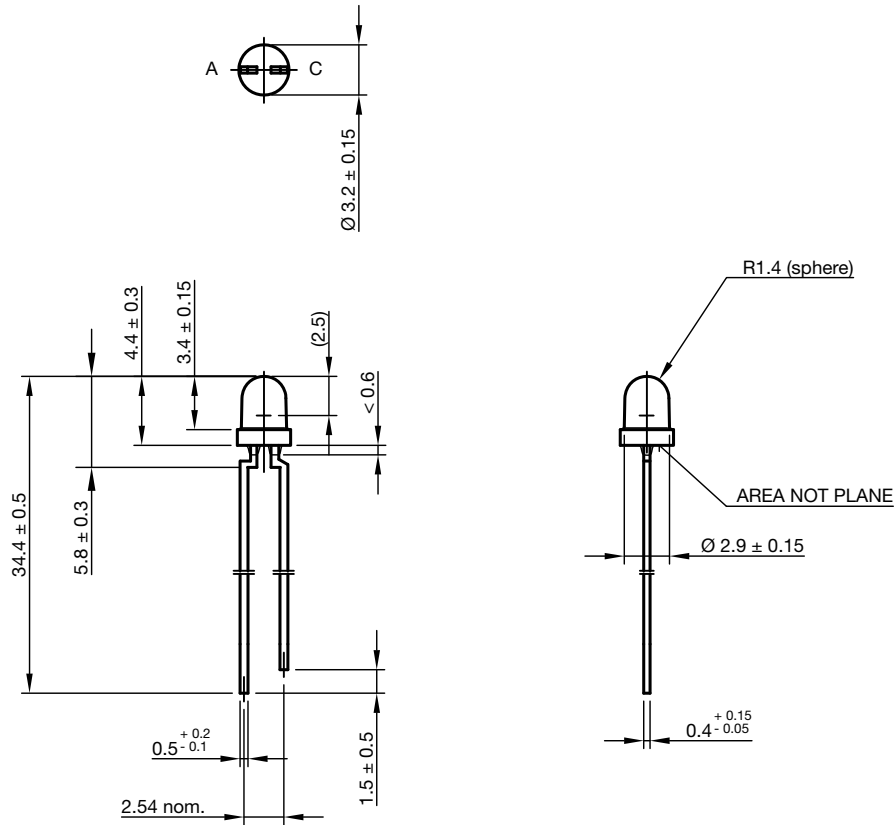


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Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.544-5255.01-4
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